

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Akito TANAKA, et al.

SERIAL NO: 10/533,237

GAU: 1641

FILED: April 29, 2005

EXAMINER:

FOR: METHOD OF IMMOBILIZING COMPOUND ON SOLID PHASE SUPPORT

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the reference(s) listed on the attached form PTO-1449. Copies of the listed reference(s) are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language reference(s).
- ☐ Online credit card payment is being made in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s), published application(s) or issued patent(s) which may be related to the present application. In accordance with the waiver of 37 CFR 1.98 dated September 21, 2004, copies of the cited pending applications are not provided. Cited published and/or issued patents, if any, are listed on the attached PTO form 1449.
- ☐ Online credit card payment is being made in the amount required under 37 CFR §1.17(p).

CERTIFICATION

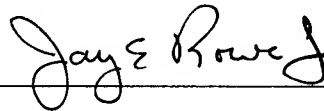
- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.
Norman F. Oblon



Customer Number

22850

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSMMN 05/03)

Jay E. Rowe, Jr.
Registration No. 58, 948

Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY DOCKET NO.

271731US0PCT

SERIAL NO.

10/533,237

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Akito TANAKA, et al.

FILING DATE

April 29, 2005

GROUP

1641

U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | FILING DATE IF APPROPRIATE |
|---------------------|----|--------------------|------------|---|-------|--------------|-------------------------------|
| | AA | 4,656,144 | 04/07/1987 | Shuntaro HOSAKA, et al. (corr. to JP 57-96260 previously filed on 04/29/2005) | | | |
| | AB | 4,879,340 | 11/07/1989 | Soyao MORIGUCHI, et al. (corr. to JP 63-48451 previously filed on 04/29/2005) | | | |
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FOREIGN PATENT DOCUMENTS

| | | DOCUMENT NUMBER | DATE | COUNTRY | TRANSLATION | |
|--|----|--------------------|------|---------|-------------|----|
| | | | | | YES | NO |
| | AO | | | | | |
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OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

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| | AW | |
| | AX | |
| | AY | |
| | AZ | |

☐ Additional References sheet(s) attached

Examiner

Date Considered

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.